



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260507000.2
Qualification of additional BOM materials for select devices
Change Notification / Sample Request

Date: May 07, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260507000.2
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMV841QMG/NOPB	NULL
LMH6601QMG/NOPB	LMH6601QMG/NOPB
LMV551QDCKRQ1	NULL
LMV931Q1MG/NOPB	595-LMV931Q1MG/NOPB
LMV841QMGX/NOPB	NULL
LMV7239QM7/NOPB	NULL
LMV931Q1MGX/NOPB	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260507000.2		PCN Date:	May 07, 2026												
Title:	Qualification of additional BOM materials for select devices															
Customer Contact:	Change Management team	Dept:	Quality Services													
Proposed 1st Ship Date:	November 03, 2026	Sample requests accepted until:	July 06, 2026													
*Sample requests received after July 06, 2026 will not be supported.																
Change Type:																
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material											
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process											
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site											
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material											
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process											
PCN Details																
Description of Change:																
This PCN is to inform of the qualification of additional BOM options for the devices in the product affected section as follows. Devices will remain at current Assembly sites.																
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>Additional</th> </tr> </thead> <tbody> <tr> <td>Wire diam/type</td> <td>0.9mil Au</td> <td>1.0mil Cu</td> </tr> <tr> <td>Mount Compound</td> <td>8075531</td> <td>4207123</td> </tr> <tr> <td>Mold Compound</td> <td>8095181</td> <td>4222918</td> </tr> </tbody> </table>						Current	Additional	Wire diam/type	0.9mil Au	1.0mil Cu	Mount Compound	8075531	4207123	Mold Compound	8095181	4222918
	Current	Additional														
Wire diam/type	0.9mil Au	1.0mil Cu														
Mount Compound	8075531	4207123														
Mold Compound	8095181	4222918														
Reason for Change:																
Continuity of supply																
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																
Review the SDP for full evaluation of the change based on the customer use case.																
Impact on Environmental Ratings:																
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																
<table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>					RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change				
RoHS	REACH	Green Status	IEC 62474													
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change													
Changes to product identification resulting from this PCN:																
None																
Product Affected:																
LMH6601QMG/NOPB	LMV7239QM7X/NOPB	LMV841QMG/NOPB														
LMV551QDCKRQ1	LMV7275IDCKRQ1	LMV841QMGX/NOPB														
LMV7239QM7/NOPB	LMV841QMG/E7002933	LMV931Q1MG/NOPB														
LMV7239QM7X/E7002934	LMV841QMG/MESN	LMV931Q1MGX/NOPB														

Qualification Report

Automotive Qualification Summary

(As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 03-April-2026

Product Attributes

Attributes	Qual Device:	Qual Device:	Qual Device:	QBS Process Reference:	QBS Package Reference:	QBS Process Reference:
	LMV551QDCKRQ1	LMV841QMG/NOPB	LMV931Q1MG/NOPB	LMV551QDCKRQ1	SN74LVC1G07QDCKRQ1	LMV824Q1MTX/NOPB
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Logic,Signal Chain	Signal Chain
Wafer Fab Supplier	MAINEFAB	MAINEFAB	MAINEFAB	MAINEFAB	FR-BIP-1	MAINEFAB
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA	TIEMA	TIEMA
Package Group	SOT	SOT	SOT	SOT	SOT	TSSOP
Package Designator	DCK	DCK	DCK	DCK	DCK	PW
Pin Count	5	5	5	5	5	14

QBS: Qual By Similarity, also known as Generic Data

Qual Device LMV551QDCKRQ1 is qualified at MSL1 260C

Qual Device LMV841QMG/NOPB is qualified at MSL1 260C

Qual Device LMV931Q1MG/NOPB is qualified at MSL1 260C

Note 1: LMV551QDCKRQ1,LMV841QMG/NOPB and LMV931Q1MG/NOPB were selected for Group A tests based on AEC-100J Appendix 1 A1.3 and A1.5.2 Multiple Families Qualification. Affected devices in PCN have justification to QBS based on

same assembly site and package attributes.

Note 2: Affected devices in PCN have justification to use Process QBS references for Group B tests based on AEC-Q100 Rev-J Appendix 1 A1.2, silicon wafer fab and die attributes were qualified. ELFR/HTOL purpose is for silicon changes and TI will

not re-run these tests for assembly/AT site changes even if AEC-Q100/ZVIE states these tests are a consideration.

Note 3: LMV841QMG/NOPB was selected for Group C tests based on AEC-100J Appendix 1 A1.3 and A1.5.2 Multiple Families Qualification. Affected devices in PCN have justification to QBS based on same assembly site and package attributes.

Note 4: LMV841QMG/NOPB were selected for Group E ED per AEC-Q100J A1.5.1 Multiple Sites - When the specific product or process attribute to be qualified or requalified will affect more than one wafer fab site or assembly site, a minimum of one

lot of testing per affected site

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device:	Qual Device:	Qual Device:	QBS Process Reference:	QBS Package Reference:	QBS Process Reference:
								LMV551QDCKRQ1	LMV841QMG/NOPB	LMV931Q1MG/NOPB	LMV551QDCKRQ1	SN74LVC1G07QDCKRQ1	LMV824Q1MTX/NOPB
Test Group A - Accelerated Environment Stress Tests													
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	1/154/0 Note 1	3/154/0 Note 1	1/77/0 Note 1	3/231/0	3/231/0 Note 1	3/154/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0 Note 1	3/231/0
ACU/HAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	1/77/0 Note 1	3/231/0 Note 1	-	3/231/0	3/231/0 Note 1	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0 Note 1	3/231/0 Note 1	1/77/0 Note 1	3/231/0	3/231/0 Note 1	-
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0 Note 1	1/5/0 Note 1	-	1/5/0	-	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	1/45/0 Note 1	3/135/0 Note 1	-	-	3/135/0 Note 1	-
Test Group B - Accelerated Lifetime Simulation Tests													
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	-	3/231/0 Note 2	-	3/231/0 Note 2
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0, Note 2	-	3/2400/0 Note 2

Test Group C - Package Assembly Integrity Tests													
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	1/30/0	3/90/0	1/30/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	1/30/0	3/90/0	1/30/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0 Note 3	-	1/15/0	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	3/30/0	1/10/0	3/30/0
Test Group D - Die Fabrication Reliability Tests													
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDD	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests													
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0 Note 4	-	3/90/0	-	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2502-016

Qualification Report

Automotive Qualification Summary (As per AEC and JEDEC Guidelines)

Q006 SOT at TIEM
Approve Date 03-April-2026

Product Attributes

Attributes	Qual Device:	Qual Device:	Qual Device:	QBS Process Reference:	QBS Package Reference:	QBS Process Reference:
	LMV551QDCKRQ1	LMV841QMG/NOPB	LMV931Q1MG/NOPB	LMV551QDCKRQ1	SN74LVC1G07QDCKRQ1	LMV824Q1MTX/NOPB
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Signal Chain	Signal Chain	Logic,Signal Chain	Signal Chain
Wafer Fab Supplier	MAINEFAB	MAINEFAB	MAINEFAB	MAINEFAB	FR-BIP-1	MAINEFAB
Assembly Site	TIEMA	TIEMA	TIEMA	TIEMA	TIEMA	TIEMA
Package Group	SOT	SOT	SOT	SOT	SOT	TSSOP
Package Designator	DCK	DCK	DCK	DCK	DCK	PW
Pin Count	5	5	5	5	5	14

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: LMV551QDCKRQ1	Qual Device: LMV841QMG/NOPB	Qual Device: LMV931Q1MG/NOPB	QBS Reference: SN74LVC1G07QDCKRQ1
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	1/154/0	3/231/0	1/77/0	3/0/0
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	1/11/0	3/33/0	1/11/0	-
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	1/11/0	3/33/0	1/11/0	-
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	QBS to SN74LVC1G07QDCKRQ1	QBS to SN74LVC1G07QDCKRQ1	QBS to SN74LVC1G07QDCKRQ1	3/231/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	QBS to SN74LVC1G07QDCKRQ1	QBS to SN74LVC1G07QDCKRQ1	QBS to SN74LVC1G07QDCKRQ1	3/231/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	1/77/0	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	1/11/0	3/33/0	1/11/0	-
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	1/3/0	3/9/0	1/3/0	-
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	1/77/0	3/231/0	1/11/0	3/231/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	175C	500 Hours	QBS to LMV841QMG/NOPB	3/135/0	QBS to LMV841QMG/NOPB	3/135/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	175C	1000 Hours	QBS to LMV841QMG/NOPB	3/135/0	QBS to LMV841QMG/NOPB	3/135/0
Test Group C - Package Assembly Integrity Tests											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	1/30/0	1/30/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	1/30/0	1/30/0

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Qual Device LMV551QDCKRQ1 is qualified at MSL1 260C
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TI Qualification ID: R-CHG-2502-016

ZVEI ID: SEM-PA-11, SEM-PA-07, SEM-PA-08

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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